

JFP Model PP5

The machines which minimal training to operate



Manual & Semi Automatic DieBonder / Placer



The die bonder model PP5 is designed for accurate placement of delicate devices on substrate.

It achieves high accuracy placement using adjustable magnification optical device.

The machine provides for single collet vacuum pick and place of die from waffle pack, wafer, Gel-Pak or bulk die media and features adjustable and repeatable subsonic scrub. The placement accuracy is < 5µm.

A robust, and reliable mechanical concept, designed to be external vibration free.

Easy to use, flexible, the PP5 requires only minimum training to operate

DIE & SUBSTRATE

- Minimum die size 150*150µm
- Maximum die size 40*40 mm (more in option)
- Substrate handling, Up to 400x350 mm.

VISION SYSTEM

- Optical Zoom 10X
- CCD Color camera high resolution
- TFT monitor 17"
- Digital crosshair
- Lighting
- Direct placement
- 2 references points for auto-centering placement
- Indexed Pick& Place Positioning

XY TABLE

- Motorized X 260mm, Y 120 mm / resolution 0.23 µm
- Motion control with progressive joystick

PARAMETERS & DISPLAY

- LCD display
- Programmable force 10gr to 600 gr
- Programmable bond time
- Programmable scrub
- Indexed Pick and Placement mode
- Vacuum selectable

OPTIONS

- Heavy duty bond head, up to 5 kg
- Eutectic / Thermocompression
- Dispenser
- Stamping
- UV
- Ultrasonic
- Flip chip
- Eject sytem for wafer
- Rework hybride
- Customized work holder
- Inspection camera
- Automatic mode

TECHNICAL SPECIFICATION

Power:	100 / 230VAC 500watt
Vacuum:	70%
Dimensions:	820*850*650mm
Weight:	80kg.
Compressed Air	5 bar

JFP Microtechnic, 1 rue du fond des prés, 91460 Marcoussis, France.

Email: jfp@jfpmicrotechnic.com, Ph +33 169313534, www.cefori.fr

www.jfpmicrotechnic.com



MICROTEST

Tél. : + 33 (0)4.90.40.60.90

Email : microtest@microtest-semi.com

Web : www.microtest-semi.com